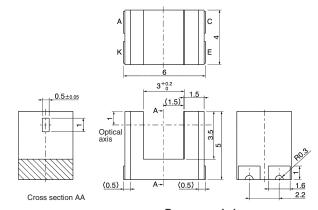
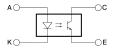
Photomicrosensor (Transmissive)

■ Dimensions

Note: All units are in millimeters unless otherwise indicated.

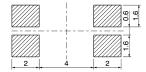


Internal Circuit



7	Terminal No.	Name	
A	4	Anode	
k	(Cathode	
		Collector	
F	=	Fmitter	

Recommended Soldering Pattern



Unless otherwise specified, the tolerances are ± 0.15 mm.

■ Features

- Ultra-compact with a 6-mm-wide sensor and a 3-mm-wide slot.
- PCB surface mounting type.
- High resolution with a 0.5-mm-wide aperture.
- RoHS Compliant.

■ Absolute Maximum Ratings (Ta = 25°C)

	Item	Symbol	Rated value
Emitter	Forward current	I _F	25 mA (see note 1)
	Pulse forward current	I _{FP}	100 mA (see note 2)
	Reverse voltage	V_R	5 V
Detector	Collector-Emitter voltage	V _{CEO}	20 V
	Emitter-Collector voltage	V _{ECO}	5 V
	Collector current	I _C	20 mA
	Collector dissipation	P_{C}	75 mW (see note 1)
Ambient	Operating	T _{opr}	-30°C to 85°C
temperature		T _{stg}	-40°C to 90°C
	Reflow soldering	T _{sol}	255°C (see note 3)
	Manual soldering	T _{sol}	350°C (see note 3)

- Note: 1. Refer to the temperature rating chart if the ambient temperature exceeds 25°C.
 - 2. Duty: 1/100; Pulse width: 0.1 ms
 - 3. Complete soldering within 10 seconds for reflow soldering and within 3 seconds for manual soldering.

■ Ordering Information

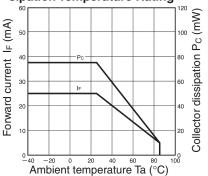
Description	Model	
Photomicrosensor (transmissive)	EE-SX1109	

■ Electrical and Optical Characteristics (Ta = 25°C)

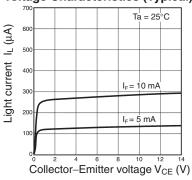
Item		Symbol	Value	Condition
Emitter	Forward voltage	V _F	1.1 V typ., 1.3 V max.	I _F = 5 mA
	Reverse current	I _R	10 μA max.	V _R = 5 V
	Peak emission wavelength	λ_{P}	940 nm typ.	I _F = 20 mA
Detector	Light current	I _L	50 μA min., 150 μA typ., 500 μA max.	$I_F = 5 \text{ mA}, V_{CE} = 5 \text{ V}$
	Dark current	I _D	100 nA max.	V _{CE} = 10 V, 0 ℓx
	Leakage current	I _{LEAK}		
	Collector-Emitter saturated voltage	V _{CE (sat)}	0.1 V typ., 0.4 V max.	$I_F = 20 \text{ mA}, I_L = 50 \mu\text{A}$
	Peak spectral sensitivity wavelength	λ_{P}	900 nm typ.	
Rising time		tr	10 μs typ.	$V_{CC} = 5 \text{ V}, \text{ R}_{L} = 1 \text{ k}\Omega, \text{ I}_{L} = 100 \mu\text{A}$
Falling time		tf	10 μs typ.	$V_{CC} = 5 \text{ V}, R_L = 1 \text{ k}\Omega, I_L = 100 \mu\text{A}$

■ Engineering Data

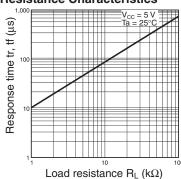
Forward Current vs. Collector Dissipation Temperature Rating



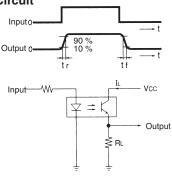
Light Current vs. Collector-Emitter **Voltage Characteristics (Typical)**



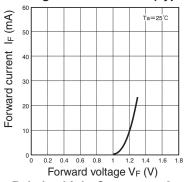
Response Time vs. Load **Resistance Characteristics**



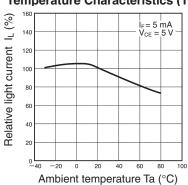
Response Time Measurement Circuit



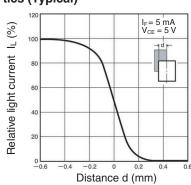
Forward Current vs. Forward **Voltage Characteristics (Typical)**



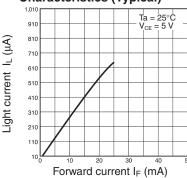
Relative Light Current vs. Ambient Temperature Characteristics (Typical)



Sensing Position Characteristics (Typical)

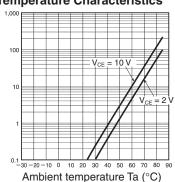


Light Current vs. Forward Current Characteristics (Typical)

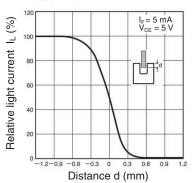


Dark Current vs. Ambient **Temperature Characteristics**

I_D (nA)

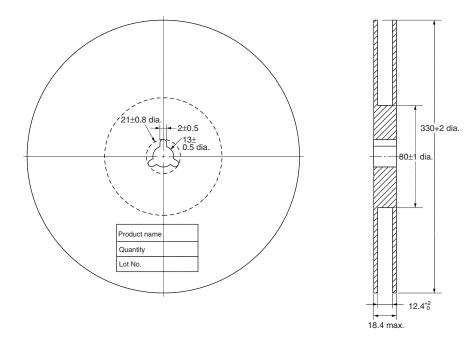


Sensing Position Characteristics (Typical)

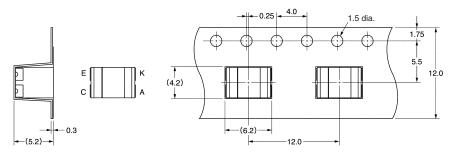


■ Tape and Reel

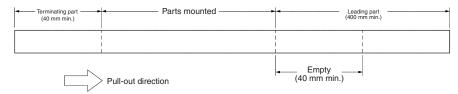
Reel



Tape



Tape configuration



Tape quantity

1,000 pcs./reel

Precautions

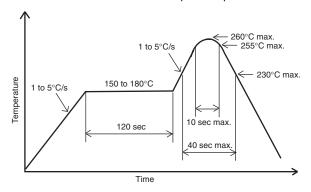
■ Soldering Information

Reflow soldering

• The following soldering paste is recommended:

Melting temperature: 216 to 220°C Composition: Sn 3.5 Ag 0.75 Cu

- The recommended thickness of the metal mask for screen printing is between 0.2 and 0.25 mm.
- Set the reflow oven so that the temperature profile shown in the following chart is obtained for the upper surface of the product being soldered.



Manual soldering

- Use "Sn 60" (60% tin and 40% lead) or solder with silver content.
- Use a soldering iron of less than 25 W, and keep the temperature of the iron tip at 300°C or below.
- Solder each point for a maximum of three seconds.
- After soldering, allow the product to return to room temperature before handling it.

Storage

To protect the product from the effects of humidity until the package is opened, dry-box storage is recommended. If this is not possible, store the product under the following conditions:

Temperature: 10 to 30°C Humidity: 60% max.

The product is packed in a humidity-proof envelope. Reflow soldering must be done within 48 hours after opening the envelope, during which time the product must be stored under 30°C at 80% maximum humidity.

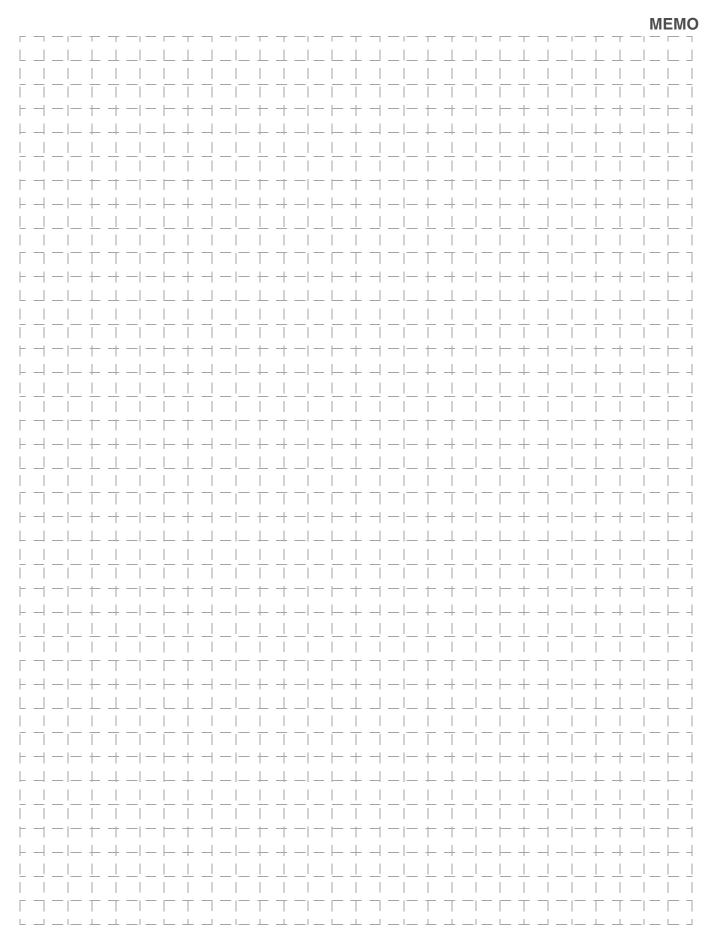
If it is necessary to store the product after opening the envelope, use dry-box storage or reseal the envelope.

Baking

If a product has remained packed in a humidity-proof envelope for six months or more, or if more than 48 hours have lapsed since the envelope was opened, bake the product under the following conditions before use:

Reel: 60°C for 24 hours or more Bulk: 80°C for 4 hours or more







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Photomicrosensor (Transmissive) **EE-SX1109**